

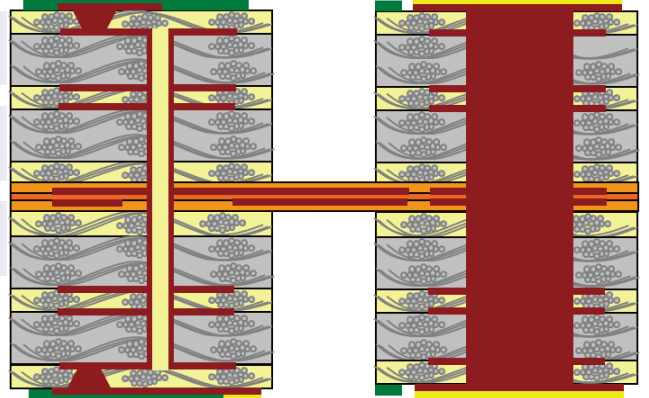
Infrastructura(Optical module)

Daisho Denshi [Flex rigid]

[Effective Thermal dissipation]

[Space saving]

[Low transmission loss material]

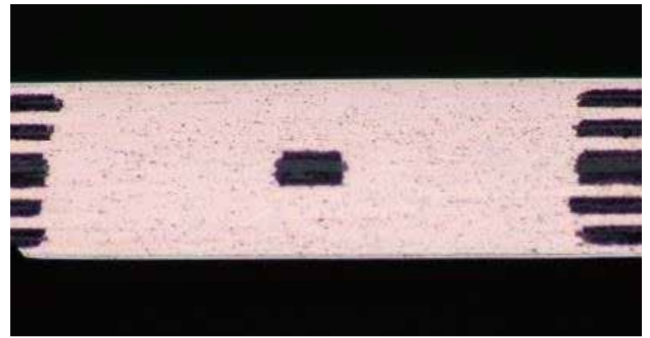


Thermal dissipation

Copper Pillar

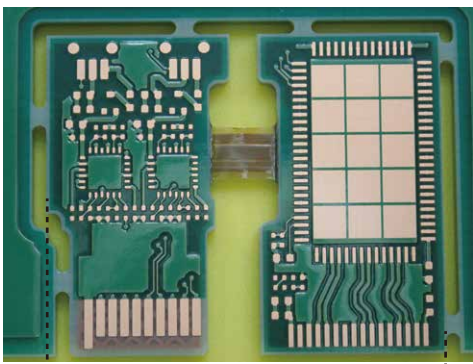


Via bar

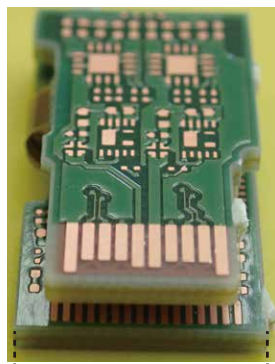


Space saving

Flex-rigid + build up



21mm



12mm

■ Effectively fit to housing

■ Connector less

■ L/S: 50um/50um

■ LVH land size: 250um

Low transmission loss material

Wide variety material-line up. Feel free to contact us.

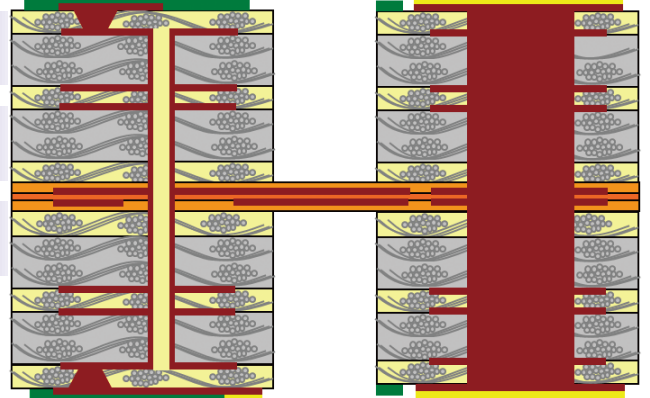
Infrastructura(Optical module)

大昌電子「フレックスリジッド」にて

「放熱対策」

「省スペース化」

「低伝送損失材料」のご提案

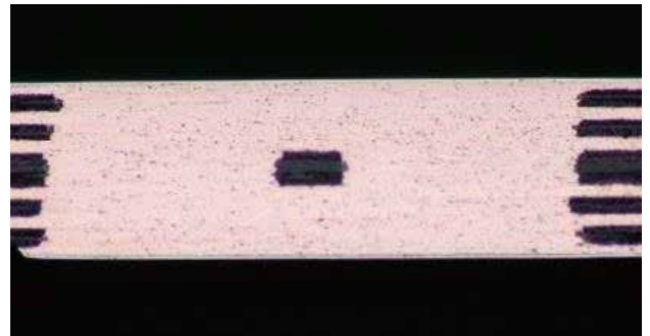


放熱対策

銅インレイ

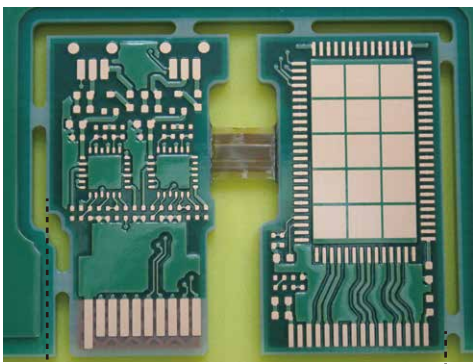


VIA-BAR

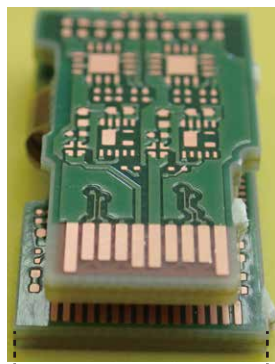


省スペース化

フレックスリジッド + ビルドアップ



21mm



12mm

■筐体内で組み込み可

■コネクタレス

■L/S:50um/50um

■LVHランド:φ250um

低伝送損失材料

材料ラインナップ多数実績有り。お気軽にご相談下さい。